

AUIRFI3205-VB Datasheet N-Channel 60 V (D-S) MOSFET

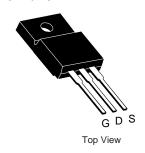
PRODUCT	SUMMARY	
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a
60	0.005 at V _{GS} = 10 V	120
80	0.013 at V _{GS} = 4.5 V	95

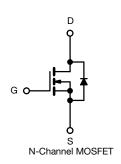
FEATURES

- 175 °C Junction Temperature
- Trench Power MOSFET
- Material categorization:



TO-220 FULLPAK





ABSOLUTE MAXIMUM RATINGS (T_C =	25 °C, unless othe	rwise noted)		
Parameter		Symbol	Limit	Unit
Gate-Source Voltage		V _{GS}	± 20	V
Continuous Daris Comment (T., 175 9CVD	T _C = 25 °C	1.	120	
Continuous Drain Current (T _J = 175 °C) ^b	T _C = 100 °C	l _D	95 ^a	
Pulsed Drain Current	•	I _{DM}	300	Α
Continuous Source Current (Diode Conduction)		I _S	70 ^a	
Avalanche Current		I _{AS}	50	
Single Avalanche Energy (Duty Cycle ≤ 1 %)	L = 0.1 mH	E _{AS}	125	mJ
Manthaus Barra Biotication	T _C = 25 °C	P _D 136		W
Maximum Power Dissipation	T _A = 25 °C	' D	3 ^b , 8.3 ^{b, c}] vv
Operating Junction and Storage Temperature Range	•	T _J , T _{stg}	- 55 to 175	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Manifestore to Amelianda	t ≤ 10 sec	R _{thJA}	15	18	
Maximum Junction-to-Ambient ^a	Steady State	¹^thJA	40	50	°C/W
Maximum Junction-to-Case		R_{thJC}	0.85	1.1	

Notes

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.
- $c.\ t \leq 10\ s.$



Parameter	Symbol	Test Conditions	Min.	Typ. ^a	Max.	Unit	
Static			L				
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	60			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	2	3	V	
Gate-Body Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1		
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 60 V, V _{GS} = 0 V, T _J = 125 °C			50	μΑ	
		V _{DS} = 60 V, V _{GS} = 0 V, T _J = 175 °C			250		
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	60			Α	
		V _{GS} = 10 V, I _D = 20 A		0.005			
D : 0	D	V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C		0.010		0	
Drain-Source On-State Resistance ^b	R _{DS(on)}	$V_{GS} = 10 \text{ V}, I_D = 20 \text{ A}, T_J = 175 ^{\circ}\text{C}$		0.015		Ω	
		$V_{GS} = 4.5 \text{ V}, I_D = 15 \text{ A}$		0.013		S	
Forward Transconductance ^b	9 _{fs}	$V_{DS} = 15 \text{ V}, I_{D} = 20 \text{ A}$		60		S	
Dynamic							
Input Capacitance	C _{iss}			5650			
Output Capacitance	C _{oss}	$V_{GS} = 0 \text{ V}, V_{DS} = 25 \text{ V}, f = 1 \text{ MHz}$		1120		pF	
Reverse Transfer Capacitance	C _{rss}			525			
Total Gate Charge ^c	Qg			47	70		
Gate-Source Charge ^c	Q_{gs}	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 50 \text{ A}$		10		nC	
Gate-Drain Charge ^c	Q _{gd}			12		1	
Turn-On Delay Time ^c	t _{d(on)}			10	20		
Rise Time ^c	t _r	V_{DD} = 30 V, R_L = 0.6 Ω		15	25		
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 50 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 2.5 \Omega$		35	50	ns	
Fall Time ^c	t _f			20	30		
Source-Drain Diode Ratings and Cha	aracteristics (T _C = 25 °C)		•			
Pulsed Current	I _{SM}			300		Α	
Diode Forward Voltage	V_{SD}	I _F = 20 A, V _{GS} = 0 V		1	1.5	V	
Reverse Recovery Time	t _{rr}	I _F = 20 A, di/dt = 100 A/μs		45	100	ns	

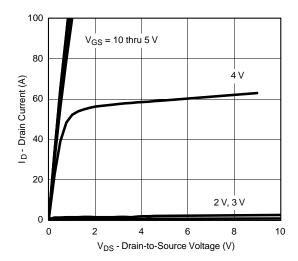
Notes:

- a. For design aid only; not subject to production testing.
- b. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- c. Independent of operating temperature.

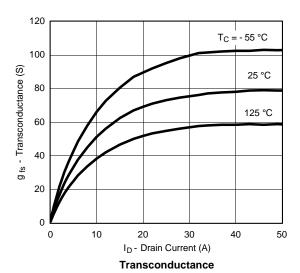
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



TYPICAL CHARACTERISTICS (25 °C unless noted)



Output Characteristics



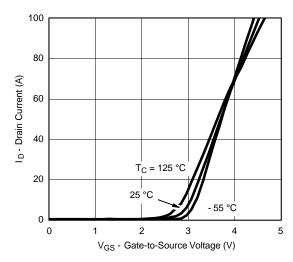
7000 6000 C_{iss} C - Capacitance (pF) 5000 4000 3000 2000 $\mathsf{C}_{\mathsf{oss}}$ 1000 $\mathsf{C}_{\mathsf{rss}}$

V_{DS} - Drain-to-Source Voltage (V) Capacitance

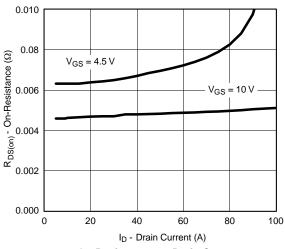
30

50

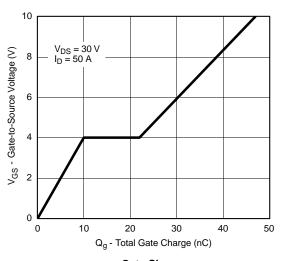
60



Transfer Characteristics



On-Resistance vs. Drain Current



Gate Charge

10

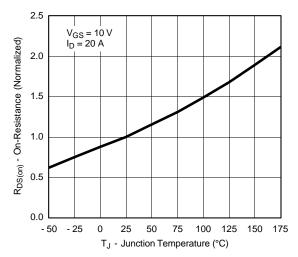
0

0

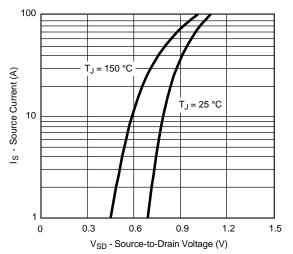
8000



TYPICAL CHARACTERISTICS (25 °C unless noted)



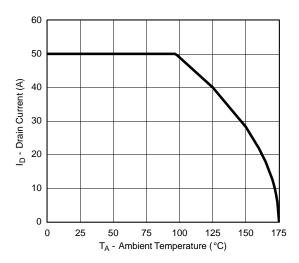
On-Resistance vs. Junction Temperature

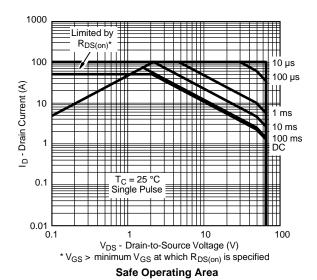


Source-Drain Diode Forward Voltage

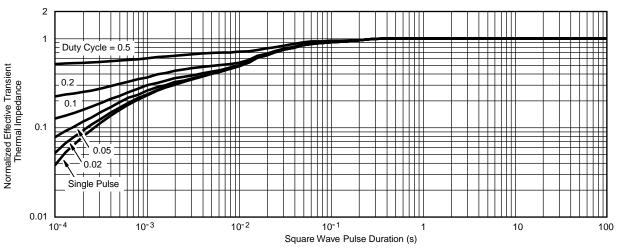


THERMAL RATINGS





Maximum Drain Current vs. Ambient Temperature



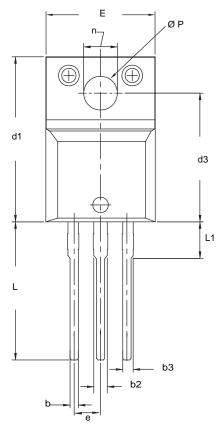
Normalized Thermal Transient Impedance, Junction-to-Case

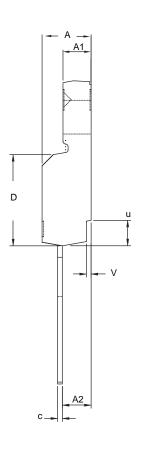
服务热线:400-655-8788

5



TO-220 FULLPAK (HIGH VOLTAGE)





DIM.	MILLIF	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.	
Α	4.570	4.830	0.180	0.190	
A1	2.570	2.830	0.101	0.111	
A2	2.510	2.850	0.099	0.112	
b	0.622	0.890	0.024	0.035	
b2	1.229	1.400	0.048	0.055	
b3	1.229	1.400	0.048	0.055	
С	0.440	0.629	0.017	0.025	
D	8.650	9.800	0.341	0.386	
d1	15.88	16.120	0.622	0.635	
d3	12.300	12.920	0.484	0.509	
E	10.360	10.630	0.408	0.419	
е	2.54	BSC	0.100 BSC		
L	13.200	13.730	0.520	0.541	
L1	3.100	3.500	0.122	0.138	
n	6.050	6.150	0.238	0.242	
ØΡ	3.050	3.450	0.120	0.136	
u	2.400	2.500	0.094	0.098	
V	0.400	0.500	0.016	0.020	

ECN: X09-0 DWG: 5972

- To be used only for process drawing.
 These dimensions apply to all TO-220, FULLPAK leadframe versions 3 leads.
 All critical dimensions should C meet C_{pk} > 1.33.
 All dimensions include burrs and plating thickness.
 No chipping or package damage.



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